Power MOSFET 30 V, 63 A, Single N–Channel, DPAK/IPAK

Features

- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- NVD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These are Pb–Free Devices

Applications

- CPU Power Delivery
- DC–DC Converters
- Low Side Switching

MAXIMUM RATINGS (T_J = 25° C unless otherwise stated)

Para	ameter		Symbol	Value	Unit
Drain-to-Source Vo	ltage		V _{DSS}	30	V
Gate-to-Source Vol	tage		V _{GS}	±20	V
Continuous Drain		$T_A = 25^{\circ}C$	۱ _D	13.8	А
Current R _{θJA} (Note 1)		T _A = 85°C		10.7	
Power Dissipation $R_{\theta JA}$ (Note 1)		T _A = 25°C	PD	2.63	W
Continuous Drain Current $R_{\theta JA}$		$T_A = 25^{\circ}C$	ID	10	А
(Note 2)	Steady State	$T_A = 85^{\circ}C$		7.8	
Power Dissipation $R_{\theta JA}$ (Note 2)	Sidle	T _A = 25°C	PD	1.4	W
Continuous Drain Current $R_{\theta JC}$	1	$T_{C} = 25^{\circ}C$	۱ _D	63	А
(Note 1)		$T_{C} = 85^{\circ}C$		49	
Power Dissipation $R_{\theta JC}$ (Note 1)		T _C = 25°C	PD	54.6	W
Pulsed Drain Current	t _p =10μs	$T_A = 25^{\circ}C$	I _{DM}	126	A
Current Limited by P	ackage	T _A = 25°C	I _{DmaxPkg}	45	А
Operating Junction a Temperature	ating Junction and Storage perature		T _J , T _{STG}	–55 to +175	°C
Source Current (Boo	ly Diode)		۱ _S	45	А
Drain to Source dV/c	dt		dV/dt	6	V/ns
Single Pulse Drain–t Energy ($V_{DD} = 24 V$, $I_L = 17 A_{pk}$, L = 1.0 n	$V_{GS} = 10 V$	Ι,	EAS	144.5	mJ
Lead Temperature for (1/8" from case for 1		Purposes	ΤL	260	°C

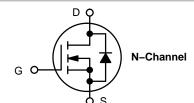
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

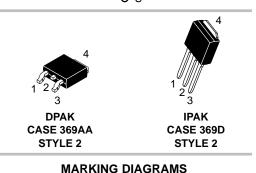


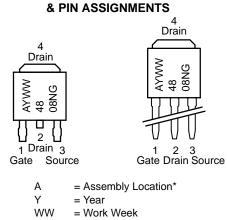
ON Semiconductor®

http://onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
00.14	8.0 mΩ @ 10 V	
30 V	12.4 mΩ @ 4.5 V	63 A







- 4808N = Device Code
- G = Pb–Free Package

* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{ extsf{ heta}JC}$	2.75	
Junction-to-TAB (Drain)	$R_{\theta JC-TAB}$	3.5	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{ hetaJA}$	57	-0/00
Junction-to-Ambient - Steady State (Note 2)	$R_{ ext{ heta}JA}$	107	

1. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.

2. Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condi	tion	Min	Тур	Мах	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				27		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 24 V	T _J = 25 °C			1	
		$V_{DS} = 24 V$	T _J = 125°C			10	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	= ±20 V			±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	= 250 μA	1.5		2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				5.6		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 to 11.5 V	I _D = 30 A		6.7	8.0	
			I _D = 15 A		6.6		mΩ
		V _{GS} = 4.5 V	I _D = 30 A		10.3	12.4	1
			l _D = 15 A		9.8		
Forward Transconductance	9 _{FS}	V _{DS} = 15 V, I _D	= 15 A		11.4		S

CHARGES AND CAPACITANCES

Input Capacitance	C _{ISS}		1538		
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 12 V	334		pF
Reverse Transfer Capacitance	C _{RSS}		180		
Total Gate Charge	Q _{G(TOT)}		11.3	13	
Threshold Gate Charge	Q _{G(TH)}		1.6		
Gate-to-Source Charge	Q _{GS}	V_{GS} = 4.5 V, V_{DS} = 15 V; I_{D} = 30 A	4.9		nC
Gate-to-Drain Charge	Q _{GD}		4.9		
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 11.5 V, V_{DS} = 15 V; I _D = 30 A	26		nC

SWITCHING CHARACTERISTICS (Note 4)

Turn–On Delay Time	t _{d(ON)}		12.3	
Rise Time	t _r	V _{GS} = 4.5 V, V _{DS} = 15 V, I _D = 15 A,	21.3	
Turn–Off Delay Time	t _{d(OFF)}	$R_G = 3.0 \Omega$	14.6	ns
Fall Time	t _f		6.0	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: pulse width \leq 300 µs, duty cycle \leq 2%. 4. Switching characteristics are independent of operating junction temperatures.

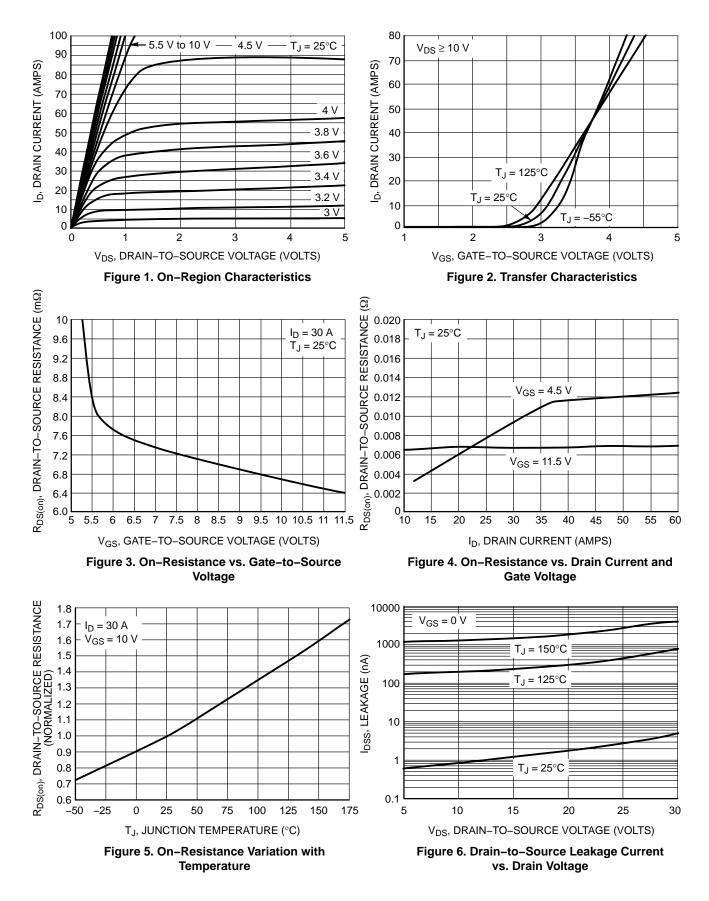
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS (M	Note 4)						
Turn-On Delay Time	t _{d(ON)}				7.7		
Rise Time	t _r	V _{GS} = 11.5 V, V	₂₅ = 15 V,		19.5		
Turn-Off Delay Time	t _{d(OFF)}	V _{GS} = 11.5 V, V I _D = 15 A, R _G	= 3.0 Ω		23		ns
Fall Time	t _f				3.5		
DRAIN-SOURCE DIODE CHARACT	ERISTICS			-			-
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V, I_{S} = 30 A T_{J} = 25^{\circ}C T_{J} = 125^{\circ}C$			0.93	1.2	
					0.83		V
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dI _S /dt = 100 A/µs, I _S = 30 A			20		
Charge Time	t _a				10.4		ns
Discharge Time	t _b				9.6		
Reverse Recovery Charge	Q _{RR}				9.7		nC
PACKAGE PARASITIC VALUES							
Source Inductance	L _S				2.49		nH
Drain Inductance, DPAK	L _D				0.0164		
Drain Inductance, IPAK	L _D	T _A = 25°	C		1.88		
Gate Inductance	L _G				3.46		
Gate Resistance	R _G				1.1		Ω

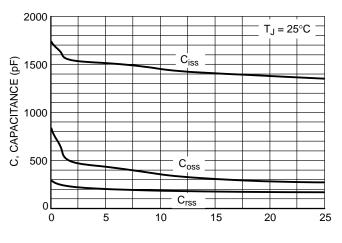
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: pulse width \leq 300 µs, duty cycle \leq 2%.

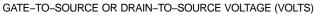
4. Switching characteristics are independent of operating junction temperatures.

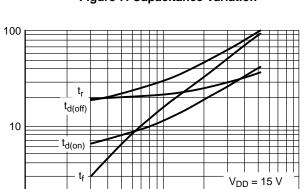
TYPICAL PERFORMANCE CURVES



TYPICAL PERFORMANCE CURVES







10

R_G, GATE RESISTANCE (OHMS)

Figure 9. Resistive Switching Time

Variation vs. Gate Resistance

t, TIME (ns)

1

1



 $I_D = 30 A$

V_{GS} = 11.5 V

100

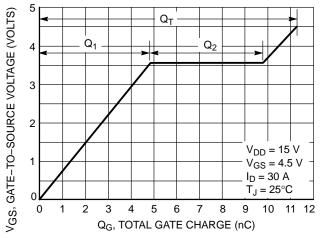


Figure 8. Gate–To–Source and Drain–To–Source Voltage vs. Total Charge

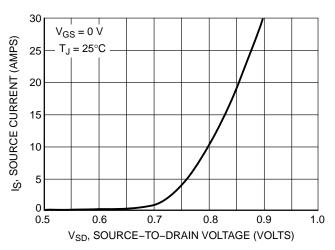
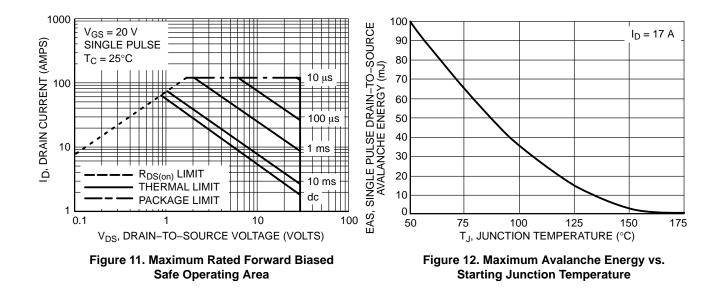


Figure 10. Diode Forward Voltage vs. Current



TYPICAL PERFORMANCE CURVES

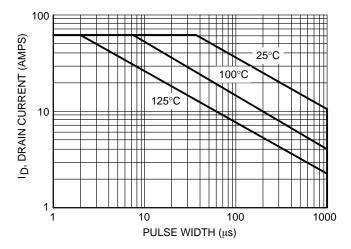
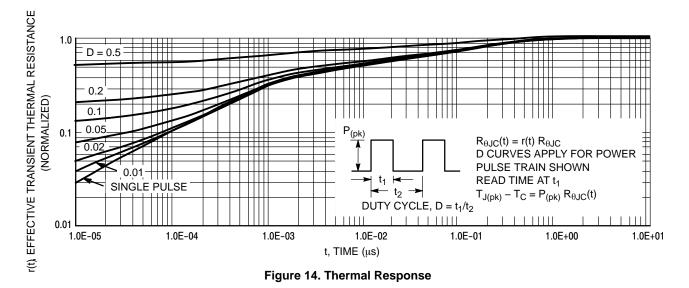


Figure 13. Avalanche Characteristics



ORDERING INFORMATION

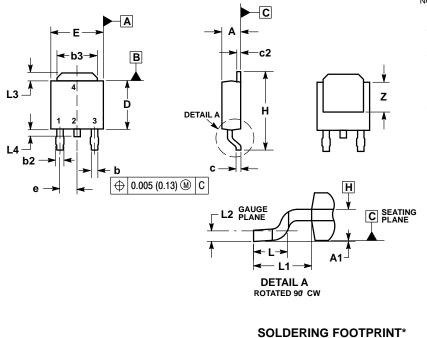
Device	Package	Shipping [†]
NTD4808NT4G	DPAK (Pb–Free)	2500 / Tape & Reel
NTD4808N-1G	IPAK (Pb–Free)	75 Units / Rail
NVD4808NT4G*	DPAK (Pb–Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NVD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

DPAK (SINGLE GUAGE) CASE 369AA **ISSUE B**

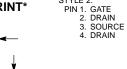


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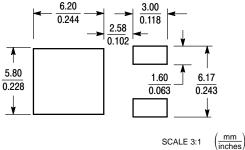
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS D3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- PLANE H.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29	BSC
Н	0.370	0.410	9.40	10.41
Г	0.055	0.070	1.40	1.78
L1	0.108	REF	2.74	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Ζ	0.155		3.93	

6.20

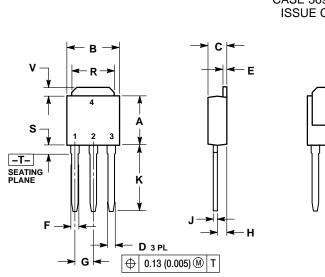


STYLE 2:

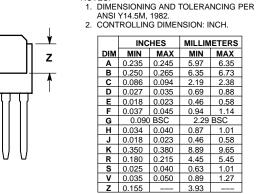


*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS







NOTES

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29	BSC
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
κ	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
۷	0.035	0.050	0.89	1.27
z	0.155		3.93	

STYLE 2: PIN 1. GATE DRAIN 2. 3. SOURCE 4 DRAIN

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